

RD Number: RD116

RD Title: TB62218AFG Evaluation circuit BOM

Item No.	Designator	Quantity	Value	Part Number	Manufacturer	Description	Package	Not Mount
1	C_VCC	1	0.1μF 25V	—	—	Chip capacitor	3.2mm×1.6mm	
2	C_VM2	1	0.1μF 50V	—	—	Chip capacitor	3.2mm×1.6mm	
3	C_VRFA	1	0.1μF 25V	—	—	Chip capacitor	3.2mm×1.6mm	
4	C_VRFB	1	0.1μF 25V	—	—	Chip capacitor	3.2mm×1.6mm	
5	C_VM1	1	100μF 50V	—	—	Electrolytic capacitor		
6	C_VDD	1	10μF 25V	—	—	Electrolytic capacitor		
7	C_OSCM	1	270pF 25V	—	—	Chip capacitor	3.2mm×1.6mm	
8	CON1	1	Connector	—	—	Connector 4P 2.5		
9	OUT_A-	1	Check terminal	—	—	Logic pin		
10	OUT_A+	1	Check terminal	—	—	Logic pin		
11	OUT_B-	1	Check terminal	—	—	Logic pin		
12	OUT_B+	1	Check terminal	—	—	Logic pin		
13	RSA	1	Check terminal	—	—	Check terminal		
14	RSB	1	Check terminal	—	—	Check terminal		
15	VCC	1	Check terminal	—	—	Check terminal		
16	VDD	1	Check terminal	—	—	Check terminal		
17	VM	1	Check terminal	—	—	Logic pin		
18	VREFA	1	Check terminal	—	—	Check terminal		
19	VREFB	1	Check terminal	—	—	Logic pin		
20	OSCM	1	Check terminal	—	—	Check terminal		
21	INA1	1	Check terminal	—	—	Check terminal		
22	INA2	1	Check terminal	—	—	Check terminal		
23	PHA	1	Check terminal	—	—	Check terminal		
24	PHB	1	Check terminal	—	—	Check terminal		
25	INB1	1	Check terminal	—	—	Check terminal		

26	INB2	1	Check terminal	—	—	Check terminal		
27	STANDBY	1	Check terminal	—	—	Check terminal		
28	GND1	1	Check terminal	—	—	Logic pin		
29	GND2	1	Check terminal	—	—	Logic pin		
30	GND3	1	Check terminal	—	—	Logic pin		
31	JP_VRF1	1	Pin header 2P	—	—	Jumper		
32		1	Jump socket	—	—	Jumper Short		
33	JP_VRF2	1	Pin header 2P	—	—	Jumper		
34		1	Jump socket	—	—	Jumper Short		
35	JP_VCC	1	Pin header 2P	—	—	Jumper		
36		1	Jump socket	—	—	Jumper Short		
37	R_MO_OUT	0	100k Ω 0.25W	—	—	Leaded resisitor		✓
38	R_OSCM	1	5.1k Ω	—	—	Chip resistor	3.2mm \times 1.6mm	
39	R_VRF1	0	Not mount	—	—	Leaded resisitor		✓
40	R_VRF2	0	Not mount	—	—	Leaded resisitor		✓
41	R_RSA	1	0.51 Ω 1W	—	—	Chip resistor	5.0mm \times 2.5mm	
42	R_RSB	1	0.51 Ω 1W	—	—	Chip resistor	5.0mm \times 2.5mm	
43	SW1	1	Pin header 3P	—	—	Jumper		
44		1	Jump socket	—	—	Jumper Short		
45	SW2	1	Pin header 3P	—	—	Jumper		
46		1	Jump socket	—	—	Jumper Short		
47	SW3	0	Pin header 3P	—	—	Jumper		✓
48		0	Jump socket	—	—	Jumper Short		✓
49	SW4	0	Pin header 3P	—	—	Jumper		✓
50		0	Jump socket	—	—	Jumper Short		✓
51	SW5	1	Pin header 3P	—	—	Jumper		
52		1	Jump socket	—	—	Jumper Short		
53	SW6	1	Pin header 3P	—	—	Jumper		
54		1	Jump socket	—	—	Jumper Short		
55	SW7	1	Pin header 3P	—	—	Jumper		
56		1	Jump socket	—	—	Jumper Short		
57	IC1	1	TB62218AFG	TB62218AFG	TOSHIBA	Motor driver IC	HSOP28	

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